

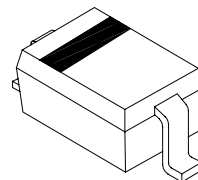


H4148SL

SWITCHING DIODE

Features

- SOD-323 Surface Mount Package
- High Breakdown Voltage
- Fast Speed Switching Time



SOD-323 Plastic Package

Absolute Maximum Ratings

Rating	Symbol	Value	Unit
Continuous Reverse Voltage	VR	100	Vdc
Peak Forward Current	IF	200	mAdc
Peak Forward Surge Current	IFM(surge)	500	mAdc

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note1) Ta=25°C Derate above 25°C	PD	225 1.8	mW mW/°C
Thermal Resistance Junction to Ambient	RθJA	556	°C/W
Total Device Dissipation Alumina Substrate (Note2) Ta=25°C Derate above 25°C	PD	300 2.4	mW mW/°C
Thermal Resistance Junction to Ambient	RθJA	417	°C/W
Junction and Storage Temperature Range	Tj, Tstg	-55~+150	°C

Note1: FR-5=1.0X0.75X0.062 in.

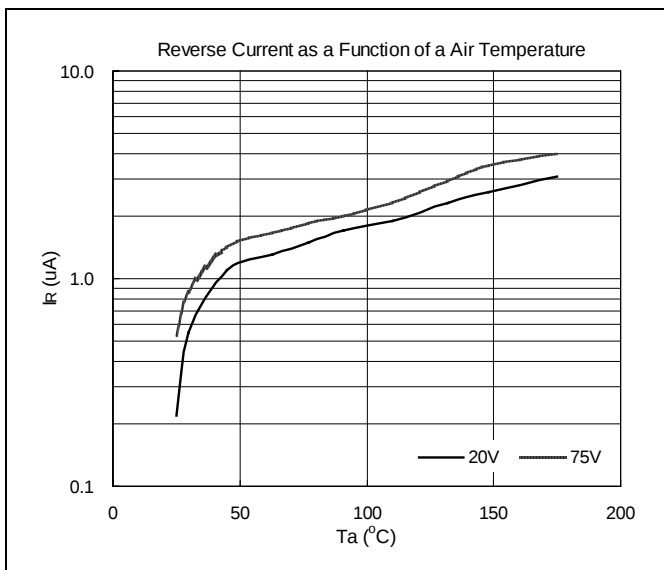
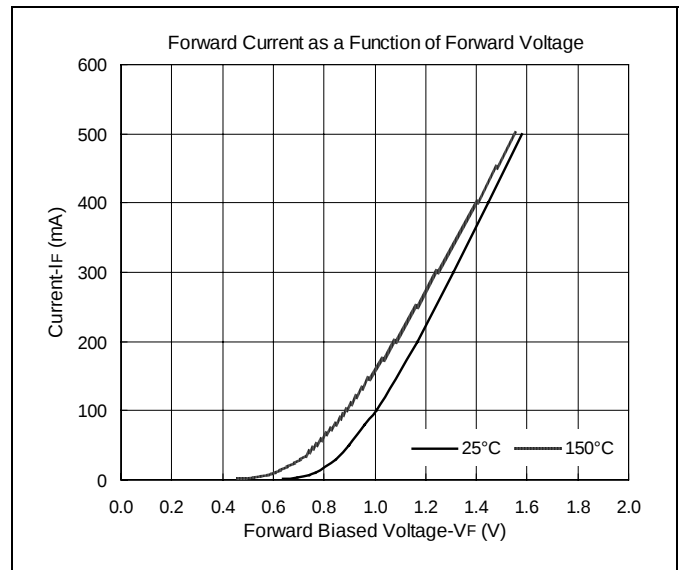
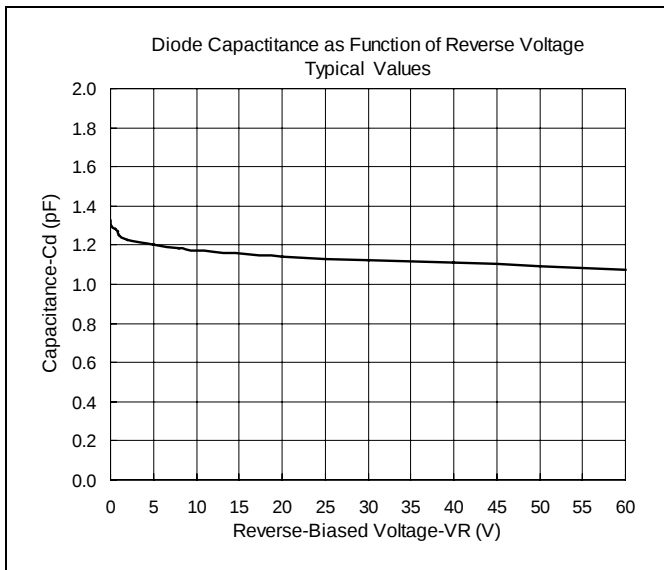
Note2: Alumina=0.4X0.3X0.024 in. 99.5% alumina

Electrical Characteristics (Ta=25°C, unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
Off Characteristics				
Reverse Breakdown Voltage (IBR=100uAdc)	V(BR)	100	-	Vdc
Reverse Voltage Leakage Current (VR=20Vdc)	IR	-	25	nAdc
Reverse Voltage Leakage Current (VR=75Vdc)		-	5	uAdc
Forward Voltage (IF=10mAdc)	VF	-	1000	mVdc
Diode Capacitance(VR=0Vdc, f=1MHz)	CD	-	4	pF
Reverse Recovery Time(IF=IR=10mAdc)	trr	-	4	ns

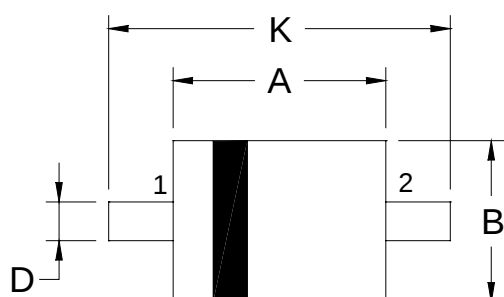


Characteristics Curve





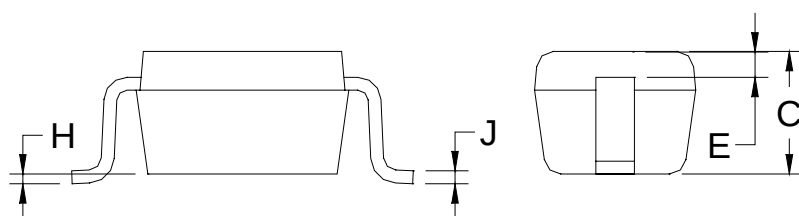
SOD-323 Dimension



Marking:



Style: Pin 1.Cathode 2.Anode



2-Lead SOD-323 Plastic Surface Mounted Package, HSMC Package Code: SL

*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0630	0.0709	1.60	1.80	E	0.0060	-	0.15	-
B	0.0453	0.0531	1.15	1.35	H	0.0000	0.0040	0.00	0.10
C	0.0315	0.0394	0.80	1.00	J	0.0035	0.0070	0.089	0.177
D	0.0098	0.0157	0.25	0.40	K	0.0906	0.1063	2.30	2.70

Notes: 1.Dimension and tolerance based on our Spec. dated DEC. 20, 2000.
2.Controlling dimension : millimeters.
3.Lead thickness specified per L/F drawing with solder plating.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy ; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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